

# MANAGEMENT SYSTEM CERTIFICATE

Certificate No:  
10000358306-MSC--KOR

Initial certification date:  
06 May, 2020

Valid:  
06 May, 2020 - 05 May, 2023

This is to certify that the management system of

## **NEPES Corporation. Cheongju 2 Campus**

587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si,  
Chungcheongbuk-do, 28116, Korea  
and the sites as mentioned in the appendix accompanying this certificate

has been found to conform to the electrostatic discharge standard  
**ANSI/ESD S20.20-2014**

This certificate is valid for the following scope:

**The manufacture of semiconductor devices including wafer bumping (Au solder plating, Cu pillar bump, redistribution layer thick Cu and Au plating) wafer probing and assembly process.**

Place and date:  
**Katy, TX, 06, May, 2020**

this audit has been performed under the  
supervision of

**Kyu Jun Hwang**

Lead Auditor



For the issuing office:  
**DNV GL - Business Assurance**  
1400 Ravello Drive, Katy, TX, 77449-  
5164, USA

A handwritten signature in black ink, appearing to read 'Chris Mauterstock'.

**Chris Mauterstock**  
Management Representative

Certificate No: 10000358306-MSC--KOR  
 Place and date: Katy, TX, 06, May, 2020

## Appendix to Certificate

### NEPES Corporation. Cheongju 2 Campus

Locations included in the certification are as follows:

Site Name	Site Address	Site Scope
NEPES Corporation. Cheongju 1 Campus	116, Gwahaksaneop 3-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28125, Korea	The manufacture of semiconductor devices including wafer bumping(Au solder plating, Cu pillar bump, redistribution layer thick Cu and Au plating)wafer probing and assembly process.
NEPES Corporation. Cheongju 2 Campus	587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28116, Korea	The manufacture of semiconductor devices including wafer bumping(Au solder plating, Cu pillar bump, redistribution layer thick Cu and Au plating)wafer probing and assembly process.

